A BELT APPARATUS

ABSTRACT

A belt apparatus and a method of conveying semiconductor packages for electroplating. The belt apparatus comprising an assembly belt; a plurality of contact plates, each contact plate comprising a head portion and a tail portion; and a plurality of resilient members arranged along a length of the assembly belt for securing the contact plates to the assembly belt and for clamping semiconductor packages to the assembly belt; wherein the tail portions of the respective contact plates contact the semiconductor packages for facilitating electroplating.

FIG. 4c